



2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Brad D. Rumsey	§	Group Art Unit:	2827
Serial No.:	09/377,286	§		
Filed:	August 18, 1999	§	Examiner:	Kamand Cuneo
For:	Positioning Flowable Solder For Bonding Integrated Circuit Elements	§	Atty. Dkt. No.:	MCT.0050US (99-325.00/US)
Cust. No.	21906	§	Conf. No.:	7573

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

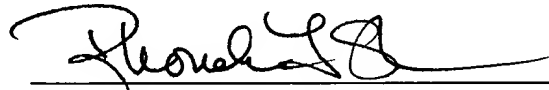
**STATUS INQUIRY**

Sir:

Applicants respectfully inquire as to the status of the above-identified application and would appreciate being informed about the next action the office may be expected to take in this application.

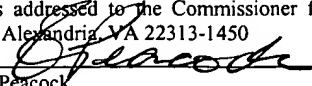
Respectfully submitted,

Date: November 17, 2004

  
Rhonda L. Sheldon, Reg. No.: 50,457  
TROP, PRUNER & HU, P.C.  
8554 Katy Freeway, Suite 100  
Houston, Texas 77024  
(713) 468-8880 [Phone]  
(713) 468-8883 [Fax]

Date of Deposit: November 17, 2004

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

  
Ellen Peacock